

UNCD Diamond Thin Film Specifications

This section applies to off-the-shelf products (custom depositions may differ)

Exclusion zone: 5 mm

Thickness: $\pm 20\%$ of target

Thickness uniformity: $< 10\%$ (Further explanation on

Electrical resistivity: Insulating diamond
Electrical resistivity
 $\leq 0.1 \text{ ohm-cm}$

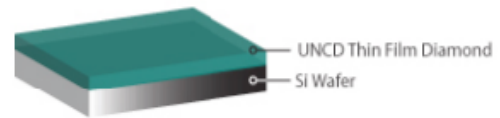
DoSi (Diamond-on-Silicon)

UNCD Wafers contain diamond (a member of the UNCD family of materials) deposited directly onto a silicon wafer.

DOI (Diamond-on-Insulator)

UNCD DOI Wafers contain $1 \mu\text{m}$ of thermal SiO_x on whole wafer, back and front side.

DoSi™ Wafer
(Diamond on Silicon)



DOI™ Wafer
(Diamond on Insulator)

